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To the Honorable Commissioner of Patents and Trademarks

ched original documents or copy thereof.

1. Name of conveying party(ies):

YASUNAGA, Shoshi; HANADA, Hideshi;
ISHIBASHI, Takahiro; SUGIMOTO, Jun;
DOHKI, Yuichi; ETOH, HitoshiAdditional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

2. Name and address of receiving party(ies)

Name: Mitsui High-tec. Inc.

Internal Address:

Street Address: 10-1, Komine 2-chome

Yahatanishi-ku,

Kitakyushu-shi

Fukuoka 806-8588 JAPAN

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: December 3, 2001

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

10/024,827

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: John S. Mortimer

Internal Address:

Wood, Phillips, VanSanten, Clark
& MortimerStreet Address: 500 West Madison Street
Suite 3800

City: Chicago State: IL ZIP: 60661

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number:

23-0785

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Nora T. Wesley

Name of Person Signing

1488.00008

Signature

02-14-2002

Date

Total number of pages including cover sheet, attachments, and document: 3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231PATENT
REEL: 012655 FRAME: 0556

ASSIGNMENT

Serial No. 10/024,827

Filed 12-17-2001

In consideration of One Dollar and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned inventor, or each inventor if more than one, hereby assigns to Mitsui High-tec. Inc. of 10-1, Komine 2-chome,
Yahatanishi-ku, Kitakyushu-shi, Fukuoka 806-8588 Japan,

its successors and assigns (hereinafter called "said assignee"), the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, entitled, LEAD FRAME FOR A SEMICONDUCTOR DEVICE, A SEMICONDUCTOR DEVICE
MADE FROM THE LEAD FRAME, AND A METHOD OF MAKING A SEMICONDUCTOR DEVICE,
executed by the undersigned on the 3rd day of Dec., 2001, and in said application and any and all other applications for United States Letters Patent, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorizes and requests the Commissioner of Patents to issue said Patent to said assignee.

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the date and serial number of said application.

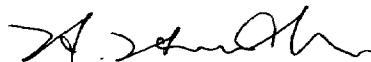
For said consideration, the undersigned hereby agrees, upon the request and at the expense of said assignee, to execute any divisional, continuation or substitute application for said invention or improvements, and any oath, declaration or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, and, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof. The undersigned agrees to perform, upon request, any affirmative acts to obtain said Letters Patent of the United States and vest in said assignee all rights therein, whereby said Letters Patent will be held and enjoyed by said assignee, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same should have been held and enjoyed by the undersigned if this assignment had not been made.

And for said consideration, the undersigned hereby assigns to said assignee the entire right, title and interest in said invention or improvements for all foreign countries, including all priority rights under

the International Convention, and agrees to execute, at the request of said assignee, all documents in connection with any application for foreign letters patent therefor.



Shoshi YASUNAGA



Hideshi HANADA



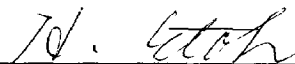
Takahiro ISHIBASHI



Jun SUGIMOTO



Yuichi DOHKI



Hitoshi ETOH

December 3, 2001

STATE OF Fukuoka

COUNTY OF Japan

Before me, a Notary Public in and for the County and State aforesaid, appeared _____

_____ to me personally known to be the signer, or signers, of the foregoing instrument, and acknowledged execution of said instrument as a free and voluntary act for the uses and purposes therein expressed.

Notary Public

WOOD, PHILLIPS, VanSANTEN, CLARK & MORTIMER
500 West Madison Street, Suite 3800
Chicago, Illinois 60661-2511